

REMARKS

The amendment to the specification corrects the name of the cited document. No new matter has been added.

The Examiner is encouraged to telephone the undersigned at (503) 222-3613 if it appears that an interview would be helpful in advancing the case.

Respectfully submitted,

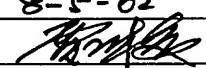
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VERSION WITH MARKINGS TO SHOW CHANGES MADE
IN THE SPECIFICATION

On page 1, line 18-21, please change paragraph as follows:

Fig. 1 is a cross-sectional view of a conventional IC device in which semiconductor chips are mounted on both sides of a lead frame in order to improve a mounting density of the package. This package structure is disclosed, for instance, in Japanese [Unexamined Patent] Utility Model Publication No. 62-147360.

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